

# 1.5A, 1000V High Efficient Surface Mount Rectifier

#### **FEATURES**

- Glass passivated chip junction
- Ideal for automated placement
- · Fast switching for high efficiency
- High surge current capability
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

#### **APPLICATIONS**

 The superior avalanche capability of BYG23M is specially suited for free-wheeling, clamping, snubber, demagnetization in power supplies and other power switching applications.

#### **MECHANICAL DATA**

- Case: DO-214AC (SMA)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- · Polarity: Indicated by cathode band
- Weight: 0.064g (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
I <sub>F</sub>	1.5	Α	
$V_{RRM}$	1000	V	
I <sub>FSM</sub>	50	Α	
$T_{JMAX}$	150	°C	
Package	DO-214AC (SMA)		
Configuration	Single die		





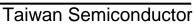




DO-214AC (SMA)



ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)				
PARAMETER	SYMBOL	BYG23M	UNIT	
Marking code on the device		BYG23M		
Repetitive peak reverse voltage	$V_{RRM}$	1000	V	
Reverse voltage, total rms value	$V_{R(RMS)}$	700	V	
Forward current	I <sub>F</sub>	1.5	Α	
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	50	Α	
Pulse energy in avalanche mode, non-repetitive (Inductive load switch off), $I_{(BR)R} = 1.23A$	E <sub>RSM</sub>	30	mJ	
Junction temperature	$T_J$	- 55 to +150	°C	
Storage temperature	T <sub>STG</sub>	- 55 to +150	°C	





THERMAL PERFORMANCE			
PARAMETER	SYMBOL	TYP	UNIT
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	70	°C/W

ELECTRICAL SPECIFICATIONS (T <sub>A</sub> = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage <sup>(1)</sup>	I <sub>F</sub> = 1A, T <sub>J</sub> = 25°C	V <sub>F</sub>	-	1.7	V
Reverse current @ rated V <sub>R</sub> <sup>(2)</sup>	T <sub>J</sub> = 25°C		-	1	μΑ
	T <sub>J</sub> = 100°C	I <sub>R</sub>	-	15	μΑ
	T <sub>J</sub> = 125°C		-	50	μA
Junction capacitance	$1MHz, V_R = 4.0V$	CJ	15	-	pF
Reverse recovery time	$I_F = 0.5A, I_R = 1.0A,$ $I_{rr} = 0.25A$	t <sub>rr</sub>	-	65	ns

# Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION			
ORDERING CODE	PACKAGE	PACKING	
BYG23M	DO-214AC (SMA)	7,500 / Tape & Reel	



## **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

**Fig.1 Forward Current Derating Curve** 

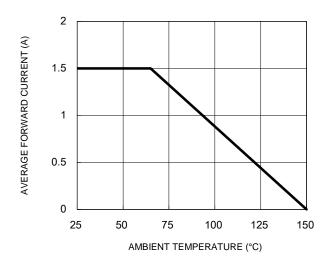


Fig.3 Typical Reverse Characteristics

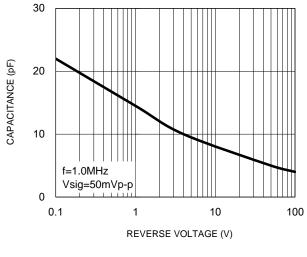
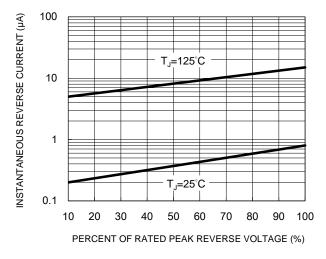


Fig.2 Typical Junction Capacitance

**Fig.4 Typical Forward Characteristics** 



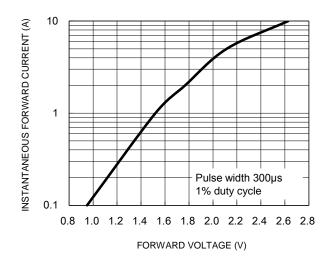
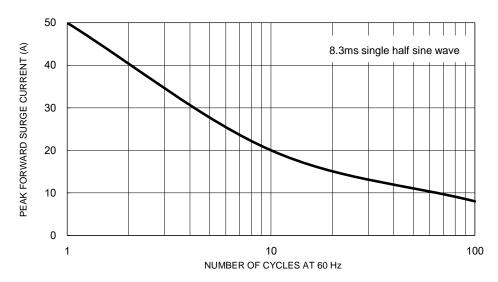


Fig.5 Maximum Non-Repetitive Forward Surge Current



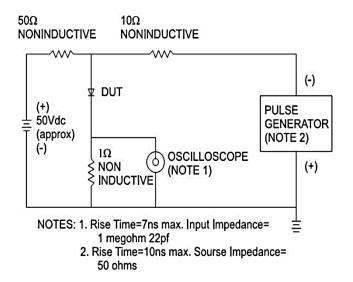


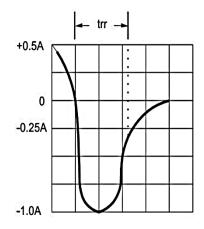


## **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

Fig.6 Reverse Recovery Time Characteristic and Test Circuit Diagram

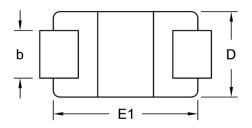


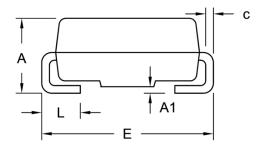




## **PACKAGE OUTLINE DIMENSIONS**

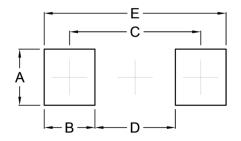
# DO-214AC (SMA)





DIM.	Unit (mm)		Unit (	Unit (inch)	
Dilvi.	Min.	Max.	Min.	Max.	
Α	1.99	2.50	0.078	0.098	
A1	0.10	0.20	0.004	0.008	
b	1.27	1.58	0.050	0.062	
С	0.15	0.31	0.006	0.012	
D	2.29	2.83	0.090	0.111	
E	4.95	5.33	0.195	0.210	
E1	4.06	4.60	0.160	0.181	
L	0.90	1.41	0.035	0.056	

## **SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
Α	1.68	0.066
В	1.52	0.060
С	3.93	0.155
D	2.41	0.095
E	5.45	0.215

## **MARKING DIAGRAM**



P/N = Marking Code G = Green Compound

YW = Date Code F = Factory Code



## **Notice**

Specifications of the products displayed herein are subject to change without notice. TSC or anyone on its behalf, assumes no responsibility or liability for any errors or inaccuracies.

Purchasers are solely responsible for the choice, selection, and use of TSC products and TSC assumes no liability for application assistance or the design of Purchasers' products.

Information contained herein is intended to provide a product description only. No license, express or implied, to any intellectual property rights is granted by this document. Except as provided in TSC's terms and conditions of sale for such products, TSC assumes no liability whatsoever, and disclaims any express or implied warranty, relating to sale and/or use of TSC products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright, or other intellectual property right.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications. Customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify TSC for any damages resulting from such improper use or sale.